



## Material Content Data Sheet



<b>Sales Product Name</b>		IDH09SG60C		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000629800						
<b>Package</b>		PG-TO220-2-1		<b>Weight*</b>		1966.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.670	0.08		849	
	noble metal	gold	7440-57-5	0.052	0.00		27	
	non noble metal	tin	7440-31-5	0.014	0.00	0.08	7	883
leadframe	non noble metal	iron	7439-89-6	1.343	0.07		683	
	inorganic material	phosphorus	7723-14-0	0.403	0.02		205	
	non noble metal	copper	7440-50-8	1341.263	68.22	68.31	682139	683027
wire	non noble metal	aluminium	7429-90-5	1.279	0.07	0.07	651	651
encapsulation	organic material	carbon black	1333-86-4	9.083	0.46		4620	
	plastics	epoxy resin	-	99.916	5.08		50815	
	inorganic material	silicondioxide	60676-86-0	496.550	25.25	30.79	252535	307970
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7368	7368
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com